

Fig.2

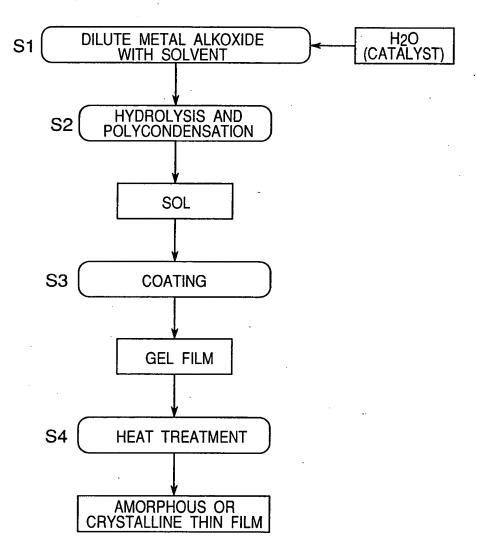


Fig.3

(1) (2) (3) (4) (5)

SOL-GEL
MATERIAL
COATING

PRE-BAKE—EXPOSURE —DEVELOPMENT—BAKING

Fig.4 PRIOR ART

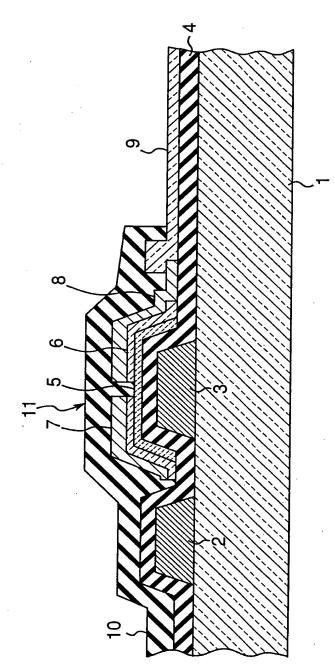


Fig.5 PRIOR ART

| POCESS | 6) | RESIST -> PRE-BAKE-> EXPOSURE-> DEVELOPMENT-> POST-BAKE-> ETCHING-> STRIPPING STRIPPING |
|--------------------------------------|-------|---|
| PPING P | | <u> </u> |
| IST STRI | (8) | PESIST RIPPING |
| ETCHING AND RESIST STRIPPING PROCESS | | <u></u> |
| | () | TCHING |
| | | 1 |
| | (9) | 1-BAKE - |
| Photoresist patterning process | ۳ | ¥ POSI |
| | | MENT — |
| | (2) | DEVELOP |
| | | ★ |
| | (4) | EXPOSU |
| | | ↑ |
| | (8) | PRE-BA |
| | | ★ |
| | (2) | ▼ RESIC COATII |
| SS | | ↑ |
| O FILM | Ξ | HLM Ation B Ttering |
| FORMIN | | SPUS |